

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

**Claim 1 (currently amended):** A probe sheet unit being a sensing section of a semiconductor wafer measuring instrument comprising:

- a base plate mountable to a prober of the instrument;
- a sheet member with a flexibility mounted to the base plate; and
- plural measurement probes provided on one surface of the sheet member, wherein each of the probes has a shape capable of elastic deformation in a direction, upward or downward the plural measurement probes are arranged on said surface of the sheet member and elastically deformable in vertical directions by respectively contacting with a plurality of electrodes arranged on a surface of a measurement objective and
- said sheet member in part or in whole is elastically deformable by a force acting thereon through the respective measurement probes and thereby is capable of vertical displacement.

**Claim 2 (currently amended):** A probe sheet unit according to claim 1, wherein wiring patterns are formed inside and/or on a surface of the sheet member and an external electrode

connected electrically to the probes through the wiring patterns is provided on the surface of the sheet member.

**Claim 3 (currently amended):** A probe sheet unit according to claim 2, wherein circuit elements are provided inside and/or on a surface of the sheet member and the circuit elements are connected electrically to the wiring patterns.

**Claim 4 (currently amended):** A probe sheet unit according to claim 1, wherein each of the probes is curved and supported at one end thereof and a reinforcing member with an elasticity higher than a probe is provided integrally with the probe on a surface thereof facing the sheet member along the length direction.

**Claim 5 (currently amended):** A probe sheet unit according to claim 1, wherein each of the probes is curved and ~~there is a predetermined clearance between a surface of a probe on the opposite side from the top of the probe at which the probe is brought into contact with an electrode of a measurement objective and the sheet member;~~ a top portion thereof is contactable with said electrodes of the measurement objective, and an reinforcement member with an elasticity higher than the probe is ~~inserted in the clearance provided on said surface of the sheet member to be located between the sheet member and an opposite side of the probe from the top thereof.~~

**Claim 6 (currently amended):** A probe sheet unit according to claim 1, wherein the sheet member is made of a material with a linear expansion coefficient in the range of from 2.5 to 10.5 ppm/\_C.

**Claim 7 (currently amended):** A probe sheet unit according to claim 1, wherein ~~which is a sensing section of a semiconductor wafer measuring instrument, comprising: a base plate mounted to a probe of the instrument; a probe sheet according to any of claims 1 to 6 mounted to a lower surface of the base plate; and an elastic member interposed between the base plate and the probe sheet~~ sheet member.

**Claim 8 (new):** A probe sheet unit comprising:  
a sheet member with a flexibility; and  
plural measurement probes provided on one surface of the sheet member, wherein  
the plural measurement probes are arranged on said surface of the sheet member and elastically deformable in vertical directions by respectively contacting with a plurality of electrodes arranged on a surface of a measurement objective and  
said sheet member in part or in whole is elastically deformable by a force acting thereon through the respective measurement probes and thereby is capable of vertical displacement.